



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE8203E		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001113312						
<b>Package</b>		PG-DSO-36-50		<b>Weight*</b>		609.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.642	1.42	1.42	14185	14185
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		373	
	non noble metal	iron	7439-89-6	4.546	0.75		7461	
wire	non noble metal	copper	7440-50-8	184.568	30.29	31.09	302928	310855
	noble metal	gold	7440-57-5	2.343	0.38	0.38	3845	3845
encapsulation	organic material	carbon black	1333-86-4	0.801	0.13		1314	
	plastics	epoxy resin	-	36.831	6.04		60450	
	inorganic material	silicondioxide	60676-86-0	362.704	59.53	65.70	595297	657061
leadfinish	non noble metal	tin	7440-31-5	5.440	0.89	0.89	8929	8929
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1298	1298
glue	plastics	epoxy resin	-	0.583	0.10		957	
	noble metal	silver	7440-22-4	1.749	0.29	0.39	2870	3827
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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